



Department of Electronics and Communication Engineering

1st International Conference

on

Electronics, Communication and Signal Processing (ICECSP 2024)

Event Format: Hybrid (In-person and Virtual)

Honorary Chair

Prof. Yogesh Singh
Vice Chancellor, University of Delhi

General Chair

Prof. (Dr.) Ajay K. Sharma
Director, NIT Delhi

Organizing Chair

Prof. Manoj Kumar
Professor, NIT Delhi

Organizing Secretaries

Dr. Rikmantra Basu
Associate Professor, NIT Delhi
Dr. Manisha Bharti
Associate Professor, NIT Delhi

Technical Program Chair

Prof. Pravin Chandra
Professor, USICT, GGSIPU

Publication Chair

Prof. Jasdeep Kaur Dhanoa
Professor, IGDUTW

Prof. Jyoteesh Malhotra

Professor, NIT Delhi

Treasurer

Dr. D. Vaithyanathan
Assistant Professor, NIT Delhi

ICECSP 2024

08th to 10th August 2024



About ICECSP 2024:

1st International Conference on Electronics, Communication, and Signal Processing (ICECSP 2024), provides a platform for researchers, academics, scholars, industry experts from India and the world to present and discuss their research findings in various areas of Electronics and Communication Engineering. However, ICECSP 2024 solicits original papers' contributions in all related areas of Electronics Engineering. The major tracks of the conference are focused on Microelectronic Circuits and Systems, Communication Systems & Networks, Signal Processing & Applications, and VLSI Technology & Embedded Systems. The conference will feature keynote speakers, technical sessions, and workshops covering a wide range of topics related to Microelectronics, VLSI Design, Signal Processing and Communication systems.

To submit your paper: [Click Here](#)

Technical Tracks

Microelectronic Circuits and Systems	Communication Systems and Networks	Signal Processing and Applications	VLSI Technology and Embedded Systems
<ul style="list-style-type: none"> Electronic Device Physics Photonic/Opto-Electronic Devices Circuits and Systems Nano-electronics System Level design Electronics for Green Technology Nano Scale Device Modeling Device Processing Techniques 	<ul style="list-style-type: none"> Optical Fibre Communication and Systems Computer & Intelligent Communication Wireless & Broadband Communication and Sensor Networks Network Security RF Antenna Design and Modelling Cognitive Communications Analog/Digital Communication Systems LTE , 5G and 6G Design 	<ul style="list-style-type: none"> Signal Processing Systems and Algorithms Radar Signal Processing Speech and Audio Signal Processing and Coding Image Signal Processing Biomedical Signal Processing and Bioinformatics Remote Sensing Applications Signal Processing Applications Computer & Intelligent Communication 	<ul style="list-style-type: none"> VLSI Design High Speed/Low Power Circuits Digital Circuits and FPGA Based Designs Analog/Mixed Signal System Design Deep Submicron Design and Modeling Issues Testing and Verification Emerging Semiconductor Technologies Real-Time Embedded Systems and Applications Distributed Embedded Computing Internet-of-Things

TIMELINE

First Round of Paper Submission	
Full Paper Submission Deadline	April 26, 2024
Acceptance Notification	On or before May 31, 2024
Final Camera-Ready Paper Submission	On or before June 15, 2024
Second Round of Paper Submission (with extended Dates)	
Full Paper Submission Deadline	May 24, 2024
Acceptance Notification	On or before June 15, 2024
Final Camera-Ready Paper Submission	On or before June 30, 2024
Registration for the Conference	
Commencement of Registration	May 10, 2024
Last date for Registration	July 05, 2024

Registration Fee Details

Category	National Participants	International Participants
Academician/Researcher (Non Member)	INR 8000/-	USD 350
Academician/Researcher (IEEE Member)	INR 7000/-	USD 300
Students (Non Member)	INR 7000/-	USD 250
Students (IEEE Member)	INR 6000/-	USD 200
Delegates (Non-Authors/Additional Authors) (IEEE Member)	INR 3000/-	USD 100
Delegates (Non-Authors/Additional Authors) (Non Member)	INR 4000/-	USD 150

Technical Sponsors:



Supporters:

